

09:00 – 19:00	Tuesday, April 21 Automotive Skills Alliance-ASA Conference (Amphitheater)
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Wednesday, April 22 <i>The participants are encouraged to attend any activity in any TRACK that would interest them (except the ones marked as restricted)</i>		
Time frame	Track 1 TECHNOLOGIES of INTERCONNECTIONS in ELECTRONICS the 35 th edition Industry-Wide Student Challenges	Track 2 TRIREME & SEMICONDUCTORS/ECSA
09:00 – 14:30	Registration & Exhibition opening - Welcome coffee <i>(1st floor hall)</i>	
09:00 – 13:00	Pannel Discussion: Needed Skills, Quality Jobs and Preparedness (Contributors: Representatives from the Industry, Academia, Government Institutions, NGOs) <i>(Amphitheater)</i>	09.00 – 17.00 TRIREME - Room 50 places <i>(Floor 1, Room 101)</i> SEMICONDUCTORS/ECSA – Room 35 places <i>(Floor 3, room 1)</i>
11:00 – 11:15	<i>Coffee Break</i> <i>(1st floor hall)</i>	
11:15 – 13:00	Workshop <i>(Amphitheater)</i>	
13:00 – 14:00	<i>Light Lunch</i> <i>(1st floor hall)</i>	
14:00 – 18:00	TIE _{EPLUS} Final Stage (public event) <i>(Amphitheater)</i>	
14:00 – 18:00	Technical meetings TIE _μ , TIE _{M PLUS} si TIE _{T PLUS} <i>(Floor 3, room 2)</i>	
18:00 – 18:30	<i>Coffee Break</i> <i>(1st floor hall)</i>	Steering Committee Meeting (RESTRICTED to Committee members)

		<i>(Floor 3, room 1)</i>	
18:30 – 19:15		TIE_{EPLUS} Demystifying the resolution of the proposed topics (Amphitheater)	
19:15		Welcome cocktail and expo networking (1st floor hall)	

Thursday, April 23			
<i>The participants are encouraged to attend any activity in any TRACK that would interest them (except the ones marked as restricted)</i>			
Time frame	Track 1 TECHNOLOGIES of INTERCONNECTIONS in ELECTRONICS the 35 th edition Industry-Wide Student Challenges		Track 2 TRIREME & SEMICONDUCTORS/ECSA
08:00 – 14:00	Registration - Welcome coffee (1 st floor hall)		09.00 – 12.15 TRIREME - Room 50 places (Floor 1, Room 101) SEMICONDUCTORS/ECSA – Room 35 places (Floor 3, room 1)
08:30 – 10:15	TIE _{MPLUS} Final Stage (public event) (Floor 1, Cafeteria)	TIE _{TPLUS} Final Stage (public event) (Floor 3, Room 2)	
10:15 – 10:30	Coffee Break (1 st floor hall)		
10:30 – 12:15	TIE _{MPLUS} Final Stage (public event) (Floor 1, Cafeteria)	TIE _{TPLUS} Final Stage (public event) (Floor 3, Room 2)	
12:15 – 13:15	Lunch (1 st floor hall)		
13:15 – 15:00	TIE _μ Final Stage (public event) (Floor 3, room 1)		
15:00 – 15:15	Coffee Break (1 st floor hall)		

Friday, April 24

*The participants are encouraged to attend any activity in any TRACK that would interest them
(except the ones marked as restricted)*

Time frame	Track 1 TECHNOLOGIES of INTERCONNECTIONS in ELECTRONICS the 35 th edition Industry-Wide Student Challenges	
	Preliminary activities	
08:00 – 08:30	TIE _E (Floor 3, room 1+2)	TIE _M (Floor 1, room 1+2)
08:30 – 12:30	TIE _E Hackathon (Floor 3, room 1+2)	TIE _M Hackathon (Floor 1, room 1+2)
12:30 – 13:30	Lunch (1 st floor hall)	
13:30 – 16:30	TIE _E Assessments (public events) (Floor 3, room 1+2)	TIE _M Assessments (public events) (Floor 1, room 1+2)
18:30 – 19:00	TIE Steering Committee Meeting (RESTRICTED to Committee members) (???? Room)	
19:00	Awarding TIE _E , TIE _M & Conclusion speeches (Amphitheater) Closure Banquet (.....)	

Saturday, April 25

Looking Forward.

Farwell discussion for the next TIE Industry-wide student challenge,

TIE 2027

(1st floor hall)

09:30 – 10:30	Looking Forward. Farwell discussion for the next TIE Industry-wide student challenge, TIE 2027 (1 st floor hall)
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